

# Product Change Notification PCN2002-08

## Change in Shipping Trays for CB Packages

---

**Description:** Xilinx is changing the shipping tray for all product manufactured in CB packages (ceramic packages with brazed leads). The current vacuum-formed shipping trays for CB packages are manufactured by Brookdale Plastics and have the following part numbers:

- BPI 612/331-7092 0-9/1.35 (for CB164, CB196, and CB228 packages)
- BPI-612/331-7092 0-9/2.53 (for CB100 packages)

The new injection-molded shipping tray is manufactured by Daewon and has the following part number:

- 1F2-63.5-419 A

The new shipping trays provide the following benefits:

- improved package lead integrity
- new trays are bakeable (maximum temperature 150°C)
- new trays are useable in automated handling equipment

Note the new shipping trays have 4 pockets, whereas the current shipping trays have 9 pockets. The new trays conform with EIA standard EIA-541. The tray drawing for the new trays can be found at:

<http://www.xilinx.com/partinfo/notify/sit0088.pdf>

Xilinx will begin using the new Daewon shipping trays starting September 11, 2002.

**Response and Contact:** Per JEDEC Standard 46-B, customers should acknowledge receipt of the PCN within 30 days of delivery of the PCN. Lack of acknowledgement of the PCN within 30 days constitutes acceptance of the change. After acknowledgement, lack of additional response within the 90-day period constitutes acceptance of the change.

For additional information or questions, please send email to the Quality Assurance group at [pcn@xilinx.com](mailto:pcn@xilinx.com), or directly by fax at (408) 369-1718.